CALL FOR PAPERS

Special Issue on
INTERCONNECTIONS AND PACKAGING
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With the advancements in MMIC and VLSI technologies, packaging of the resultant high speed digital, RF, microwave and millimeter integrated circuits and systems in a cost effective and high performance manner has become a major challenge. This special issue will review recent advances in the analysis, design, fabrication and volume production of packaging for RF, microwave and millimeter wave MMICs and hybrid circuits and highlight the applications of these techniques to the development of high speed, high density digital and mixed signal RF integrated circuits and modules. In light of the recent profusion of commercial microwave and high speed digital applications, special attention will be paid to those technologies aimed at high volume, low cost packaging.

Topics of particular interest include, but are not limited to, the following areas:

- New materials for packages to improve electrical or thermal properties
- Circuit and electromagnetic modeling and simulation of interconnects and packages including vias, bends, crossovers, wire bonds, multi-conductor structures, leaky-waves, ...
- Advanced time and frequency domain measurement and characterization techniques
- Computer aided design, engineering and manufacturing
- MMIC modules and packaging
- Packaging for wireless communication circuits and systems
- Embedded passives and 3-D packaging
- Low cost, high volume packages
- Reliability considerations
- High speed optoelectronic packages
- Micron and submicron multilayer interconnects for ULSI/GSI, chip scale integration

Rick Sturdivant of Hughes Aircraft Company and Vijai Tripathi of Oregon State University will be guest editors of this special issue. Prospective authors are requested to submit four copies of their manuscript describing original work in the above mentioned areas by January 5, 1997, to:

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